EE 330 Quiz #05

Name: Score

Grader:

Briefly answer the following questions:

1. Circle the best conductor: Iron, Copper, Graphene, Aluminum
2. Circle the most widely used metal for wiring in IC: Iron, copper, gold, aluminum
3. Circle the most widely used metal for wire bonding during chip packaging: Iron, copper, gold, aluminum
4. Rank the following layers in conductivity from highest (1) to lowest (5):
   * Gate poly 3
   * P-substrate 5
   * Top metal 1
   * N-well 4
   * Metal 1 2 in sheet resistance, also 1 in rho
5. Rank the area capacitance density from highest (1) to lowest (5)”
   * Ploy to substrate 2
   * Poly to active 1
   * Poly to metal 1 3
   * Top metal to substrate 5
   * Metal 1 to substrate 4